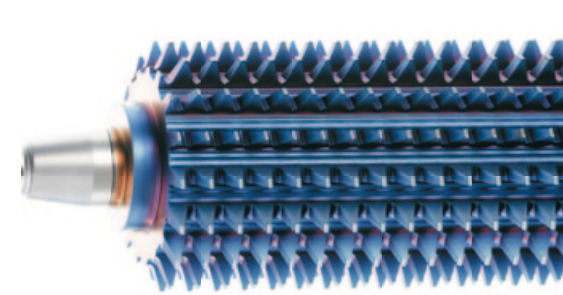


DC SPUTTER COATING SYSTEM



CemeCon coating systems with DC Sputter technology are especially flexible and applicable universally. For many years they have been the backbone of many tool coatings around the world. Depending on the quantities required, the ML and XL versions are available. Both of them coat quickly and easily with all nitride-, boride- and carbon-based materials. Add-on modules allow further individual adjustments.

The **CC800[®]/9 ML** is the economical system for medium unit quantities and frequent changes in batch and coating

material. With the optional flex module, your capacity can be further enlarged and quickly adapted to current order volume. Due to its high flexibility, the CC800[®]/9 ML line has proved its worth in research and development. The system's open, modular design allows it to be equipped with many extensions and options, such as measuring devices. If necessary, it can be equipped with HiPIMS or pulse modules, among others.

CemeCon has developed the **CC800[®]/9 XL** for large unit quantities or large components. With the same external dimensions as the ML model, it has considerably larger

coating volume. It coats 4.500 drills or 16.400 cutting inserts and tools up to 800 millimeters long and 650 millimeters in diameter in just one operation. The electro-hydraulically driven quick-change table allows fast loading and unloading of tool batches.

		CC800 [®] /9 ML 6 (10)	CC800 [®] /9 XL
Coating area Ø x h	[mm]	Ø400 x 400 (Ø650 x 400)	Ø650 x 700
Substrate table Ø x number of satellites	[mm] number	Ø400 x Ø130 x 6 (Ø650 x Ø130 x 10)	Ø650 x Ø130 x 10
Quick replacement table		Mechanical or electro-hydraulic	Electro-hydraulic
Sputter cathodes	items [mm]	4 x 500	4 x 800
Maximum substrate dimensions Ø x h	[mm]	Ø400 x 800 (Ø650 x 800)	Ø650 x 800
Drill capacity Ø6 mm x 60 mm	item	1,800 (3,000)	4,500
Insert capacity 12.7 mm x 3.5 mm	item	4,920 (8,200)	16,400
Maximum substrate weight	[kg]	250 (500)	500
Cycle time for 3 µm Hyperlox [®] *	[h]	5	6
Processes		Sputtering with booster technology	Sputtering with booster technology
Substrate pre-treatment (plasma etching)		Booster and MF etching	Booster and MF etching
Electrically conductive coatings		Yes	Yes
Electrically non-conductive coatings		No	No
Electrically non-conductive substrates		No	No
Rated power	[kW]	60	80
Power consumption per batch for 3µm Hyperlox [®] *	[kWh]	120	200
Outer dimensions (w x l x h)	[mm ³]	1,050 x 3,350 x 2,200	1,050 x 3,350 x 2,200
Weight (empty)		3,000 – 3,300	~ 3,300

* On a 10 mm milling cutter

DC-MAGNETRON-SPUTTERN

Cathode



DC

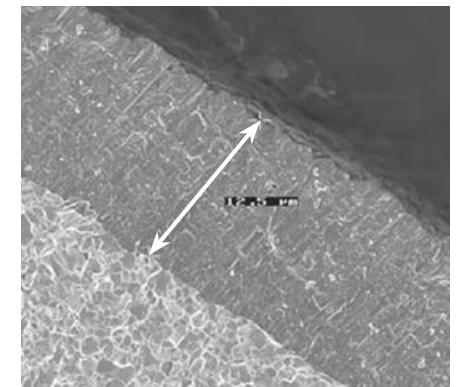
BIAS



DC

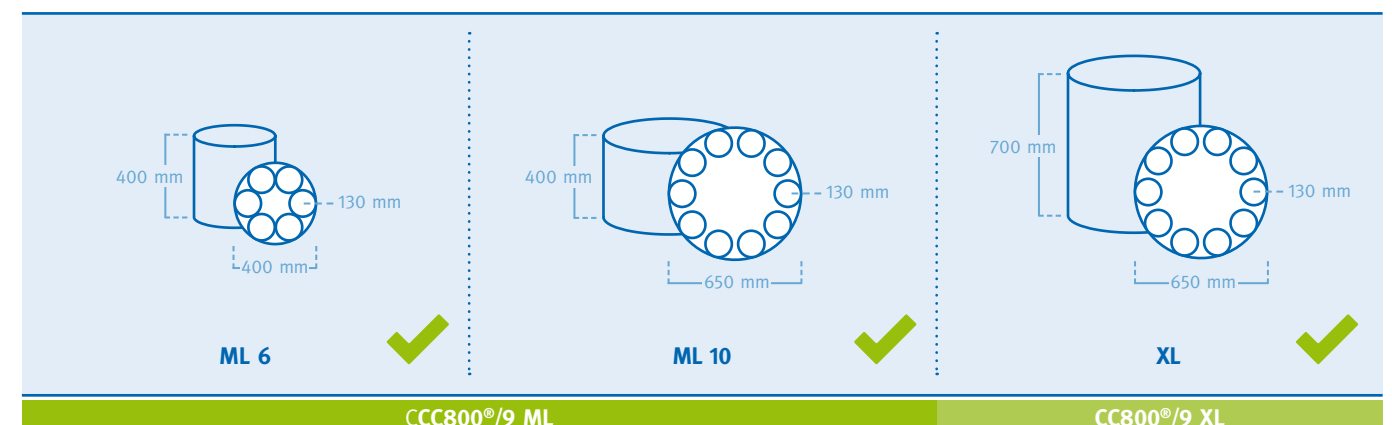


Puls



ALOX[®] SN² coating with 12.5 µm coating thickness

COATING VOLUME



CC800[®]/9 ML

CC800[®]/9 XL